

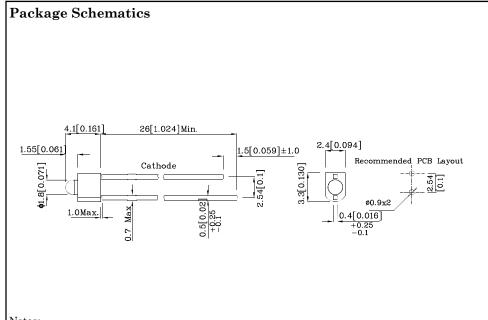
1.8mm INFRARED EMITTING DIODE

Features

- Radial / Through hole package
- \bullet Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS Compliant







Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		Yellow (GaAsP/GaP)	Unit		
Reverse Voltage	$V_{\rm R}$	5	V		
Forward Current	I_{F}	30	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA		
Power Dissipation	P_{D}	75	mW		
Operating Temperature	$T_{\rm A}$	-40 ~ +85			
Storage Temperature	Tstg	-40 ~ +85	°C		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)		Yellow (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	1.95	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.5	V
Reverse Current (Max.) $(V_R=5V)$	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λР	590*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	588*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	20	pF

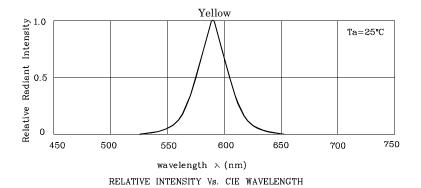
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I _F =10mA) mcd		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XLUY61D-A	Yellow	GaAsP/GaP	Yellow Diffused	4*	7*	590*	70°

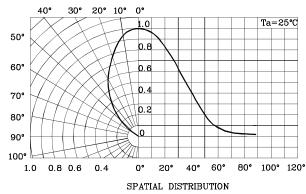
 $^{^*}$ Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Sep 29,2016

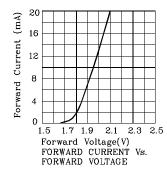


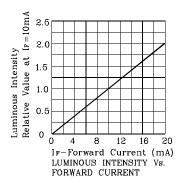


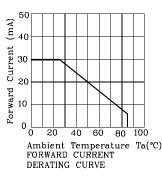


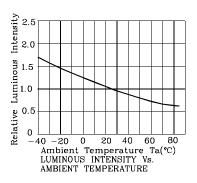


❖ Yellow

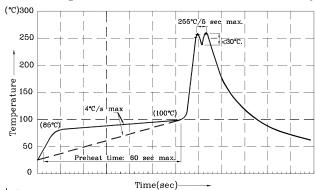








Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

- Notes. I. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of $260^{\circ}C$ 2. Peak wave soldering temperature between $245^{\circ}C \sim 255^{\circ}C$ for 3 sec
- (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above $85\,^\circ\text{C}.$ 4.Fixtures should not incur stress on the component when mounting and
- during soldering process. 5.SAC 305 solder alloy is recommended.
- 6. No more than one wave soldering pass

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

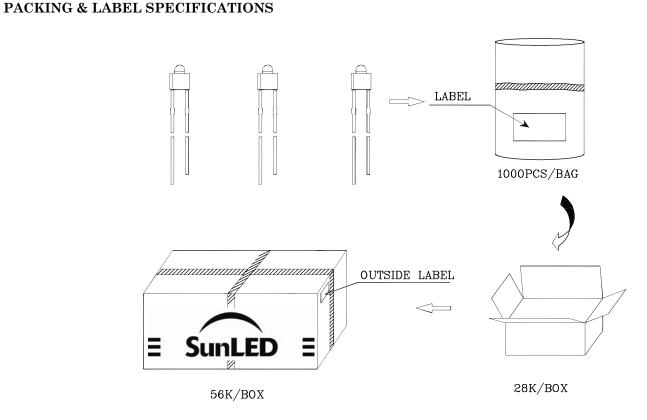
the typical accuracy of the sorting process is as follows:

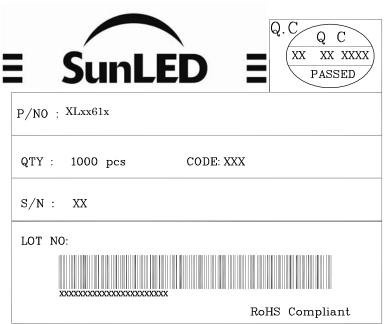
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



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Sep 29,2016

XDSB8796 V1-Z Layout: Maggie L.